

# 1N4148SWS

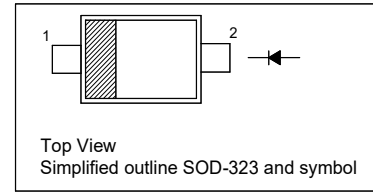
## Silicon Epitaxial Planar Switching Diode

### Features

- Fast switching

### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



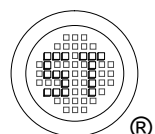
### Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	$V_{RM}$	100	V
Reverse Voltage	$V_R$	75	V
Average Rectified Forward Current	$I_{F(AV)}$	150	mA
Forward Continuous Current	$I_{FM}$	300	mA
Surge Forward Current	$I_{FSM}$	2 1	A
		at $t < 1 \mu\text{s}$ at $t < 1 \text{s}$	
Power Dissipation	$P_D$	200	mW
Operating Junction Temperature	$T_j$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	- 65 to + 150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient <sup>1)</sup>	$R_{\theta JA}$	625	$^\circ\text{C/W}$

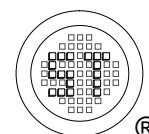
<sup>1)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



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## Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at $I_R = 1 \mu\text{A}$	$V_{(BR)R}$	75	-	V
Forward Voltage at $I_F = 1 \text{ mA}$ at $I_F = 10 \text{ mA}$ at $I_F = 50 \text{ mA}$ at $I_F = 150 \text{ mA}$	$V_F$	- - - -	0.715 0.855 1 1.25	V
Peak Reverse Current at $V_R = 75 \text{ V}$ at $V_R = 20 \text{ V}$ at $V_R = 75 \text{ V}, T_J = 150^\circ\text{C}$ at $V_R = 25 \text{ V}, T_J = 150^\circ\text{C}$	$I_R$	- - - -	1 25 50 30	$\mu\text{A}$ nA $\mu\text{A}$ $\mu\text{A}$
Total Capacitance at $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	$C_T$	-	2	pF
Reverse Recovery Time at $I_{rr} = 0.1 \times I_R, I_F = 10 \text{ mA}, V_R = 6 \text{ V}, R_L = 100 \Omega$	$t_{rr}$	-	4	ns



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## Electrical Characteristics Curves

Fig 1. Power Derating Curve

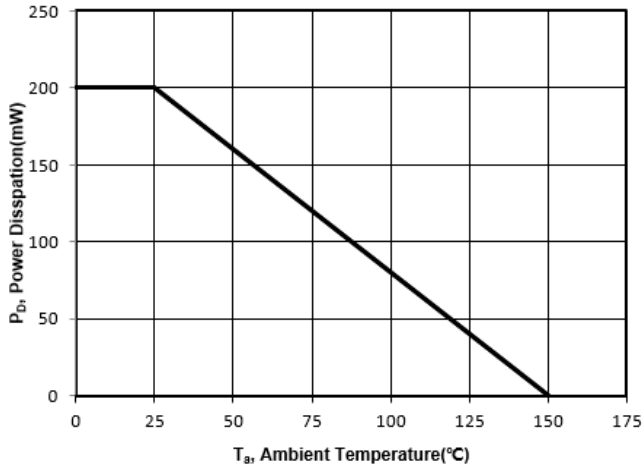


Fig 2. Capacitance Characteristics

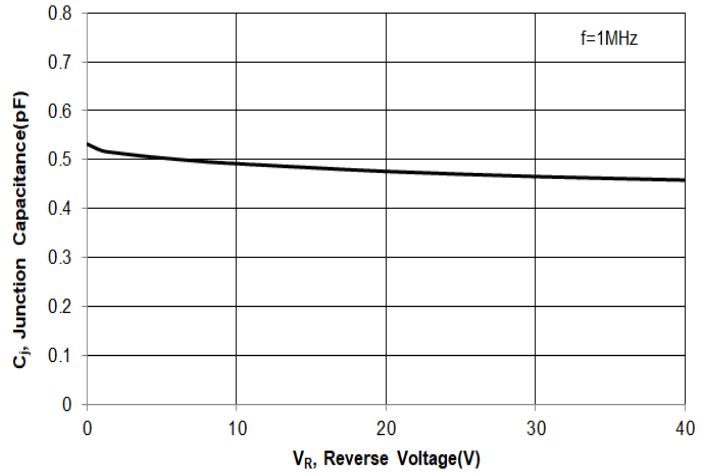


Fig 3. Reverse Characteristics

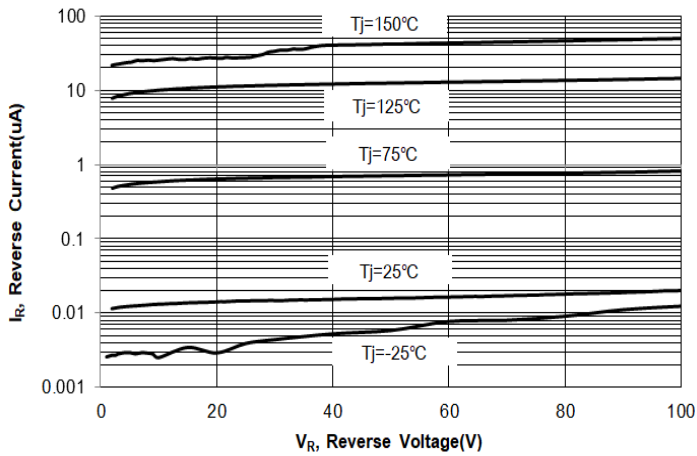
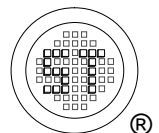
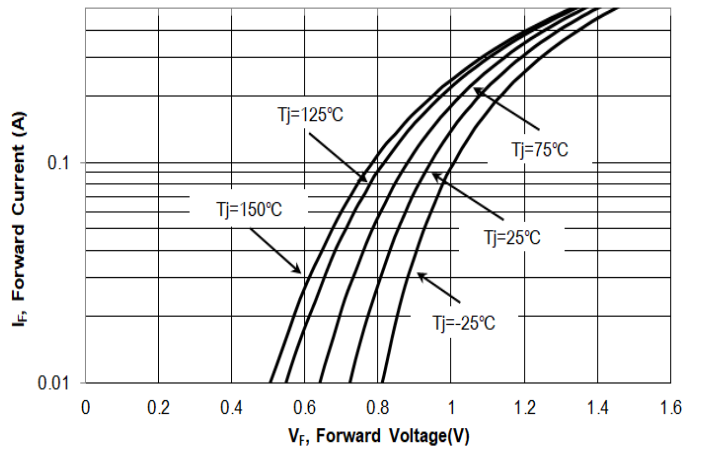


Fig 4. Forward Characteristics

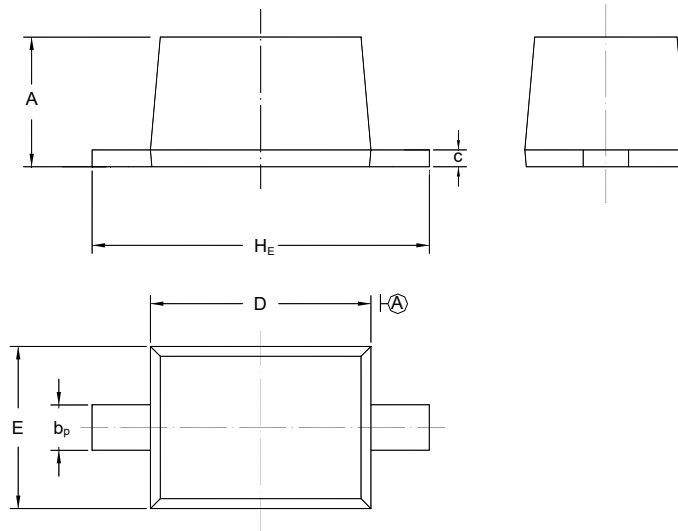


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## PACKAGE OUTLINE

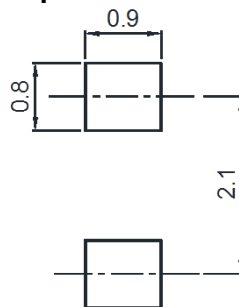
Plastic surface mounted package; 2 leads

SOD-323



UNIT	A	b <sub>p</sub>	C	D	E	H <sub>E</sub>
mm	1.10 0.80	0.40 0.25	0.15 0.10	1.80 1.60	1.35 1.15	2.80 2.30

### Recommended Soldering Footprint

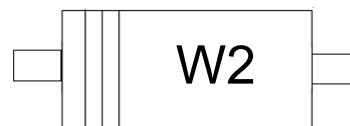


### Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOD-323	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

### Marking information

" W2 " = Part No  
 " III " = Cathode line  
 Font type: Arial



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